SDZS003A - OCTOBER 1989 - REVISED OCTOBER 1990

- 10KH Compatible
- ECL and TTL Control Inputs
- Noninverting Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Center Pin V_{CC}, V_{EE}, and GND Configurations Minimize High-Speed Switching Noise
- Package Options Include "Small Outline" Packages and Standard Plastic 300-mil DIPs

description

This octal ECL-to-TTL translator is designed to provide a efficient translation between a 10KH ECL signal environment and a TTL signal environment. This device is designed specifically to improve the performance and density of ECL-to-TTL CPU/bus-oriented functions such as memory-address drivers, clock drivers, and bus-oriented receivers and transmitters.

Two output-enable pins, $\overline{OE}1$ and $\overline{OE}2$, are provided. These control inputs are ANDed together with $\overline{OE}1$ being ECL compatible and $\overline{OE}2$ being TTL compatible. This offers the choice of controlling the outputs of the device from either a TTL or ECL signal environment.

The SN10KHT5541 is characterized for operation from 0°C to 75°C.

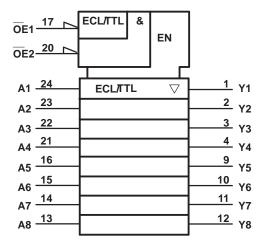
FUNCTION TABLE

OUT	PUT	DATA	OUTPUT		
ENABLE		INPUT	(TTL)		
OE1	OE2	Α	Y		
Х	Н	Х	Z		
Н	Х	Х	Z		
L	L	L	L		
L	L	Н	Н		

(TOP VIEW) 24 A1 Y2 **∏** 2 23 A2 Y3 **∏** 3 22 A3 21 A4 Y4 🛮 4 20 OE2 (TTL) V_{CC} $\lceil 5 \rceil$ GND 6 19 V_{EE} 18 GND GND 7 GND **∏** 8 17 OE1 (ECL) Y5 **∏** 9 16 A5 Y6 **1** 10 15 A6 Y7 [14 A7 11 13 A8 **Y8** [

DW OR NT PACKAGE

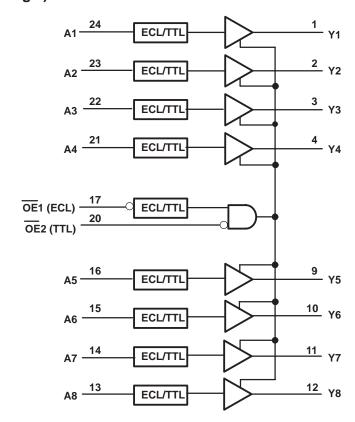
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	0.5 V to 7 V
Supply voltage, V _{EE}	8 V to 0 V
Input voltage (TTL) (see Note 1)	1.2 V to 7 V
Input voltage (ECL)	V _{EE} to 0 V
Voltage applied to any output in the disabled or power-off state	. −0.5 V to 5.5 V
Voltage applied to any output in the high state	\dots -0.5 V to V _{CC}
Input current (TTL)	-30 mA to 5 mA
Current into any output in the low state	96 mA
Operating free-air temperature range	0°C to 75°C
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The TTL input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

			MIN	NOM	MAX	UNIT	
V _{CC} TTL supply voltage				5	5.5	V	
VEE	V _{EE} ECL supply voltage				-5.46	V	
VIH	TTL high-level input voltage		2			V	
VIL	TTL low-level input voltage				0.8	V	
		T _A = 0°C	-1170		-840		
∨ _{IH} ‡	ECL high-level input voltage	T _A = 25°C	-1130		-810	mV	
		T _A = 75°C	-1070		-735		
		T _A = 0°C	-1950		-1480		
∨ _{IL} ‡	ECL low-level input voltage	T _A = 25°C	-1950		-1480	mV	
		T _A = 75°C	-1950		-1450		
liK	TTL input clamp current				-18	mA	
ІОН	High-level output current				-15	mA	
lOL	Low-level output current				48	mA	
TA	Operating free-air temperature		0		75	°C	

[‡] The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic levels only.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		MIN	TYP [†]	MAX	UNIT					
٧ıK	OE2 only	$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -4.94 \text{ V},$	$I_{ } = -18 \text{ mA}$				-1.2	V		
II	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	V _I = 7 V				0.1	mA		
lΗ	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	V _I = 2.7 V				20	μΑ		
Ι _Ι L	OE2 only	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	V _I = 0.5 V				-0.5	mA		
		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_{I} = -840 \text{ mV}$	T _A = 0°C			350			
lн	Data inputs and OE1	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_{I} = -810 \text{ mV}$	T _A = 25°C			350	μА		
		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_{I} = -735 \text{ mV}$	T _A = 75°C			350			
					$T_A = 0^{\circ}C$	0.5					
I _I L	Data inputs and OE1	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_{I} = -1950 \text{ mV}$	T _A = 25°C	0.5			μΑ		
					T _A = 75°C	0.5					
V/	-	$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -5.2 \text{ V} \pm 5\%,$	IOH = -3 mA		2.4	3.3		V		
VOH		$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -5.2 \text{ V} \pm 5\%,$	$I_{OH} = -15 \text{ mA}$		2	3.1		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		
VOL		$V_{CC} = 4.5 \text{ V},$	$V_{EE} = -5.2 \text{ V} \pm 5\%,$	I _{OL} = 48 mA			0.38	0.55	V		
lozh		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_0 = 2.7 \text{ V}$				50	μΑ		
lozL		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_0 = 0.5 V$				-50	μΑ		
los‡		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V},$	$V_O = 0$		-100		-225	mA		
ICCH		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V}$				64	97	mA		
ICCL		$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V}$				80	120	mA		
ICCZ	·	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V}$		·		77	116	mA		
IEE	·	$V_{CC} = 5.5 \text{ V},$	$V_{EE} = -5.46 \text{ V}$		·		-22	-33	mA		
Ci	·	$V_{CC} = 5 V$,	V _{EE} = −5.2 V		·		5		pF		
Co		$V_{CC} = 5 V$,	V _{EE} = −5.2 V				7		pF		

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 5 V, V_{EE} = -5.2 V, T_A = 25°C.

switching characteristics over recommended ranges of operating free-air temperature and supply voltage (see Figure 1)

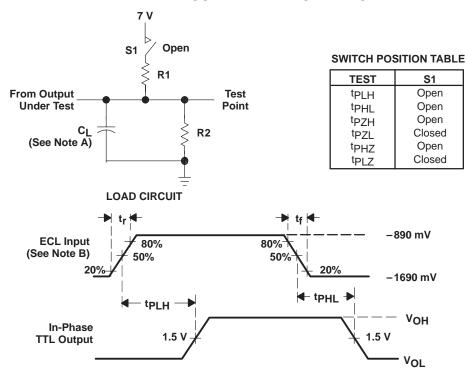
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C R R	UNIT		
			MIN	TYP§	MAX	
^t PLH	А		1.7	4	6.2	
^t PHL	A	Ţ	1.6	4	6.2	ns
^t PZH	OE1	Y	2.6	4.7	6.7	
t _{PZL}	OE1	, r	3.2	5.9	8.5	ns
^t PHZ	OE1	V	2.9	5.4	7.8	ns
t _{PLZ}	OL1	'	1.9	4.9	7.8	
^t PZH	ŌE2	Υ	1.7	4	6.2	ns
^t PZL	OLZ	1	2.5	5.1	7.7	1115
^t PHZ	ŌĒ2	Υ	2.1	4.3	6.4	
[†] PLZ	UE2	Y	1.1	3.7	6.3	ns

 $[\]overline{\$}$ All typical values are at $V_{CC} = 5$ V, $V_{EE} = -5.2$ V, $T_A = 25$ °C.



[‡] Not more than one output should be tested at a time and the duration of the test should not exceed 10 ms.

PARAMETER MEASUREMENT INFORMATION



3 V -890 mV **ECL Output** Output Control Control 50% 50% 1.5 V (Low-level 1.5 V (Low-level enabling enabling) (See Note B) -1690 mV (See Note B) **tPZL tPZL** tPLZ → tPLZ-3.5 V 3.5 V Output Output Waveform 1 50% Waveform 1 50% (See Note D) VOL +0.3/6L (See Note D) V_{OL} +0.3 V VOL tPZH tPHZ tPHZ → ^tPZH Vон VOH Output V_{OH} -0.3 V V_{OH} -0.3 V Output Waveform 2 50% Waveform 2 (See Note D) 50% (See Note D) n 0 TTL ENABLE AND DISABLE TIMES **ECL ENABLE AND DISABLE TIMES**

ECL-INPUT PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.

- B. For TTL inputs, input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50~\Omega$, $t_\Gamma \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- C. For ECL inputs, input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$, $t_f \leq$ 0.7 ns, $t_f \leq$ 0.7 ns.
- D. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- E. The outputs are measured one at a time with one transition per measurement.

FIGURE 1. LOAD CIRCUIT AND VOLTAGE WAVEFORMS



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN10KHT5541DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	(5) Level-1-260C-UNLIM	0 to 70	10KHT5541
SN10KHT5541DW.A	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	10KHT5541

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

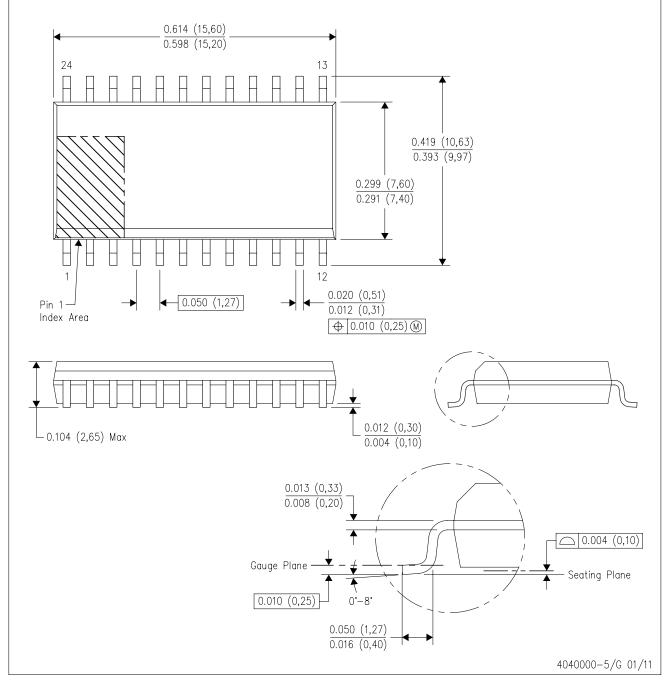


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN10KHT5541DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN10KHT5541DW.A	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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